

Digital IC Design

Lec 1: Overview & Design Methodology

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General Information

■ Instructor : Professor Po-Tsang (Bug) Huang

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- ◆ Office Hours: After class or by appointment @ MIRC 601

■ Regular class hours

- ◆ Monday 1:20 AM – 4:20 PM

Grading of this Course

- **20% Exercises**

- ◆ On-line choice questions for Each Lecture

- **60% Labs (self-evaluation for your grades)**

- ◆ Tools: Verilog, HSPICE
- ◆ Most exercises are related to circuit-level implementation

- **20% Final Team Project**

Undergraduate Course v.s. Graduate Course

■ **Undergraduate courses (VLSI)**

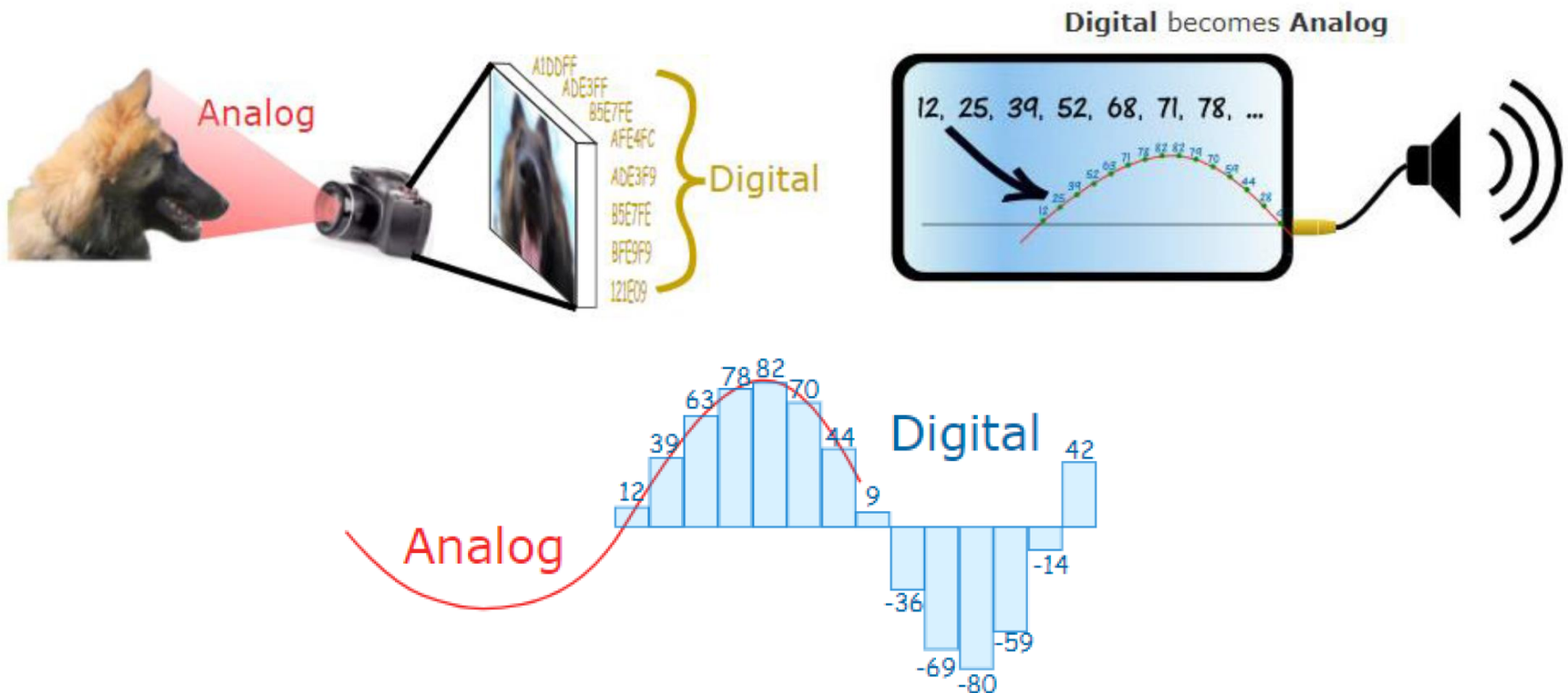
- ◆ Basic transistor and circuit models
- ◆ Basic circuit design styles
- ◆ First experiences with design – creating a solution with given numbers of specifications

■ **Graduate courses**

- ◆ Transistor models of varying accuracy
- ◆ Design under constraints: power-constrained, flexible, robust,...
- ◆ Learning the more advanced techniques
- ◆ Study the challenges facing design in the near future
- ◆ Creating new solutions to challenging design problems

Digital Processing or Digital Computing

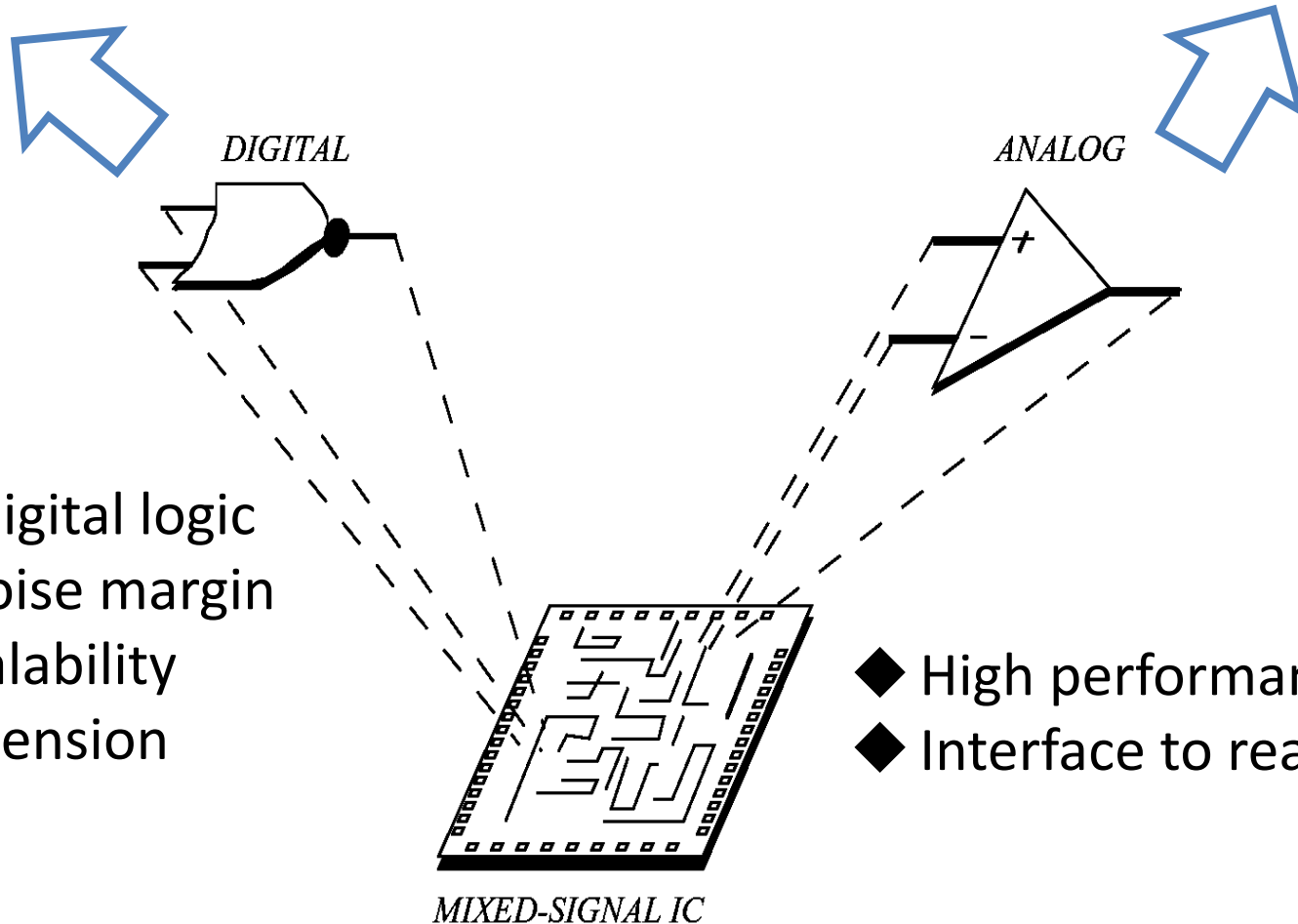
- Analog real world v.s. digital computing system
 - ◆ Discrete digital data (binary digits: 0 & 1)



Digital Circuits and Analog Circuits

Software

Sensor, power



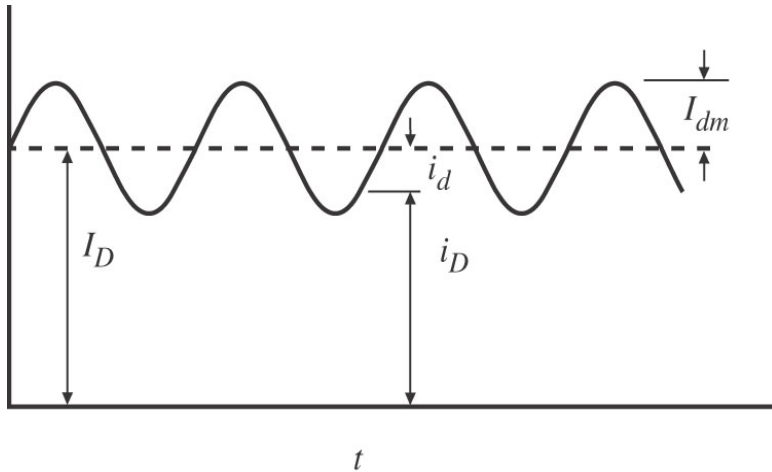
- ◆ Dense digital logic
- ◆ Large noise margin
- ◆ High scalability
- ◆ Easy extension

- ◆ High performance
- ◆ Interface to real world

Signal Characteristics

■ Analog signals

◆ DC + Small signals



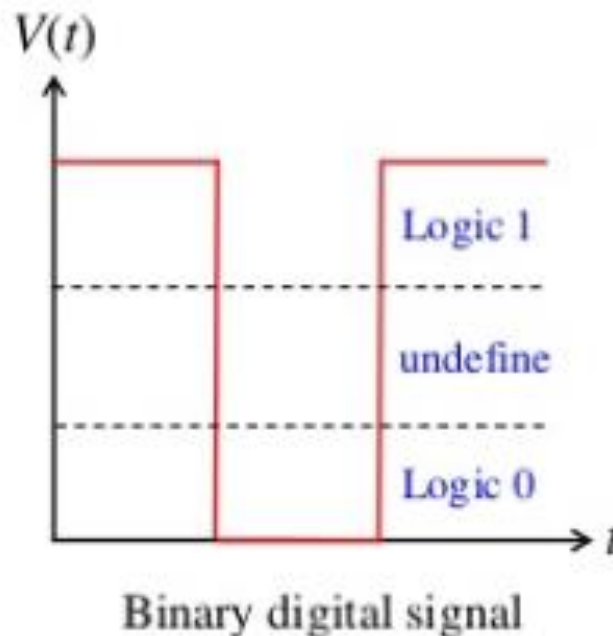
■ Digital binary signals

◆ 0 & 1

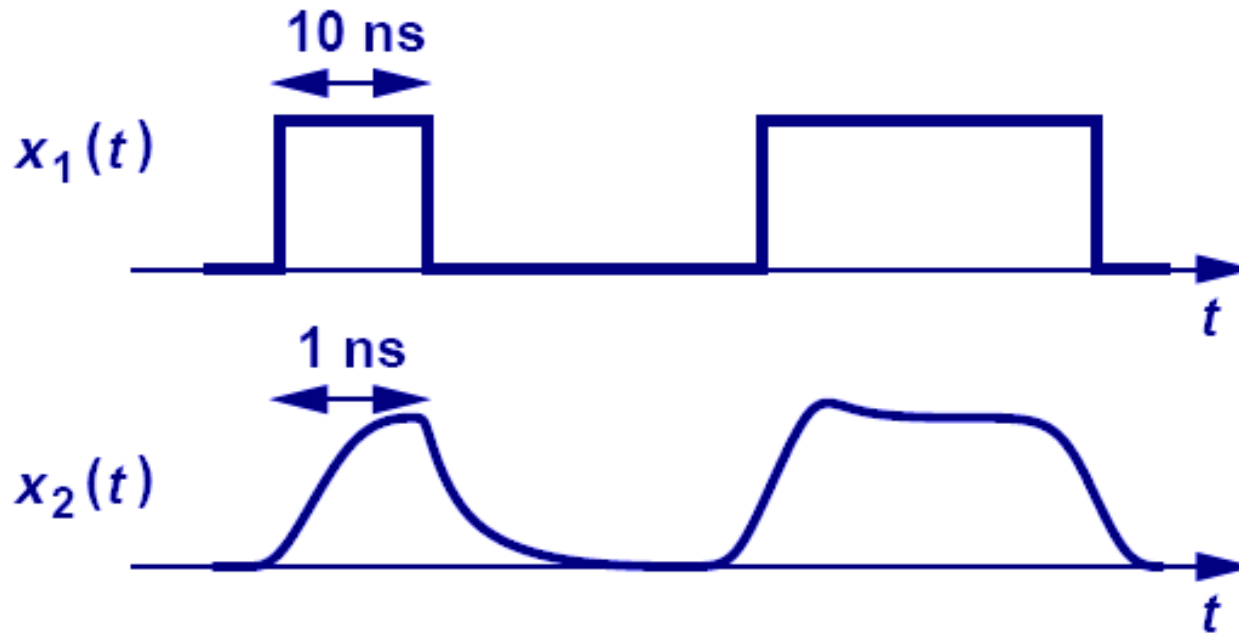


Binary Digital Signal

- An information variable represented by physical quantity.
- Binary values are represented abstractly by:
 - ◆ Digits 0 and 1
 - ◆ Words (symbols) False (F) and True (T)
 - ◆ Words (symbols) Low (L) and High (H)
 - ◆ And words on and off
- Binary values are represented by ranges of values of physical quantities.



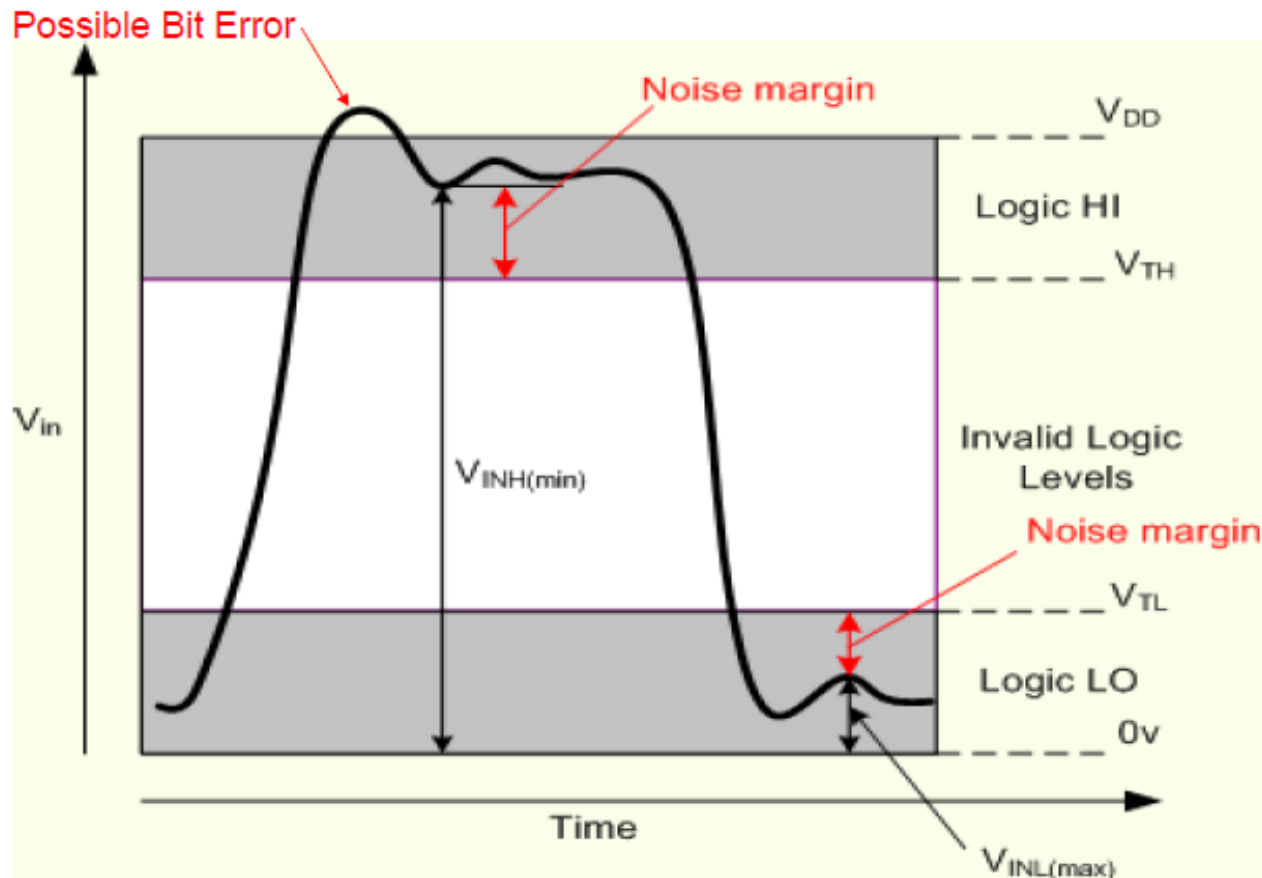
Digital or Analog Signal?



- $x_1(t)$ is operating at 100Mb/s and $x_2(t)$ is operating at 1Gb/s.
- A digital signal operating at very high frequency is very “analog”.

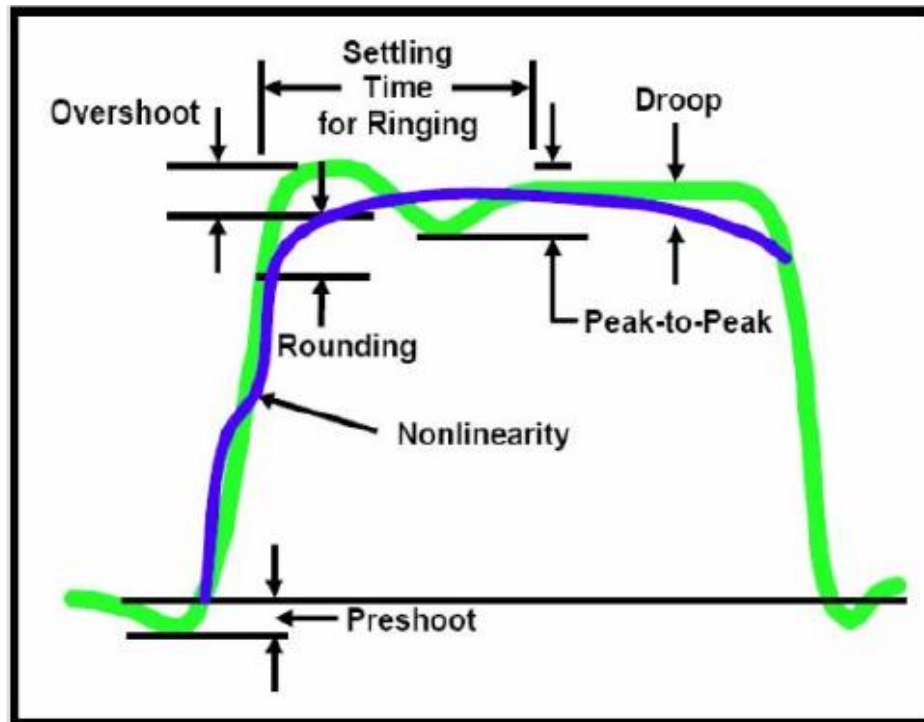
Binary Logic Level

- The signal voltage must make into the “End Zone” within the allotted period of time.

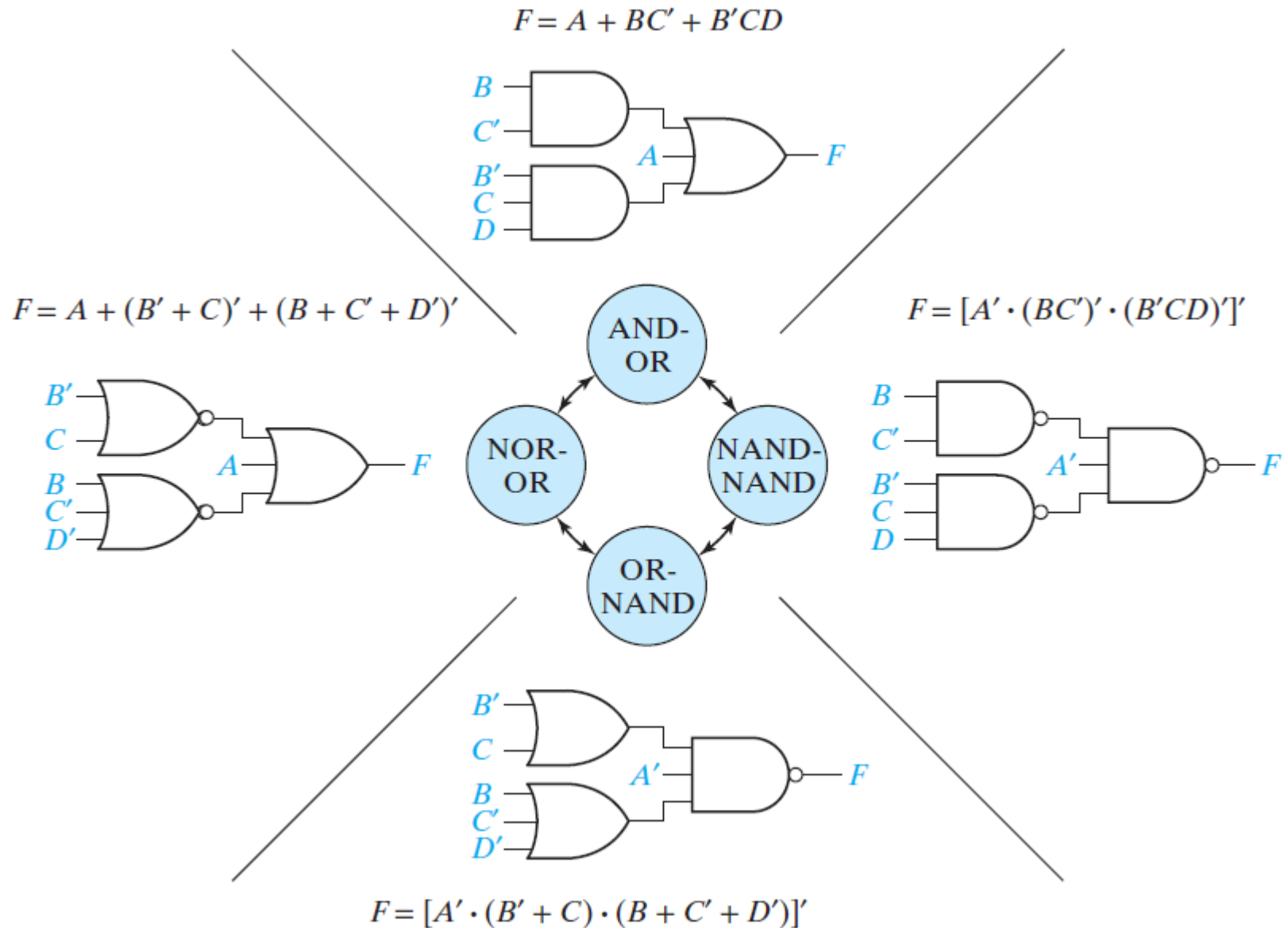


Introduction to Signal Aberration

- Power noises (power integrity)
- Parasitic R,L,C
- Coupling effect
- Non-continuous physical links

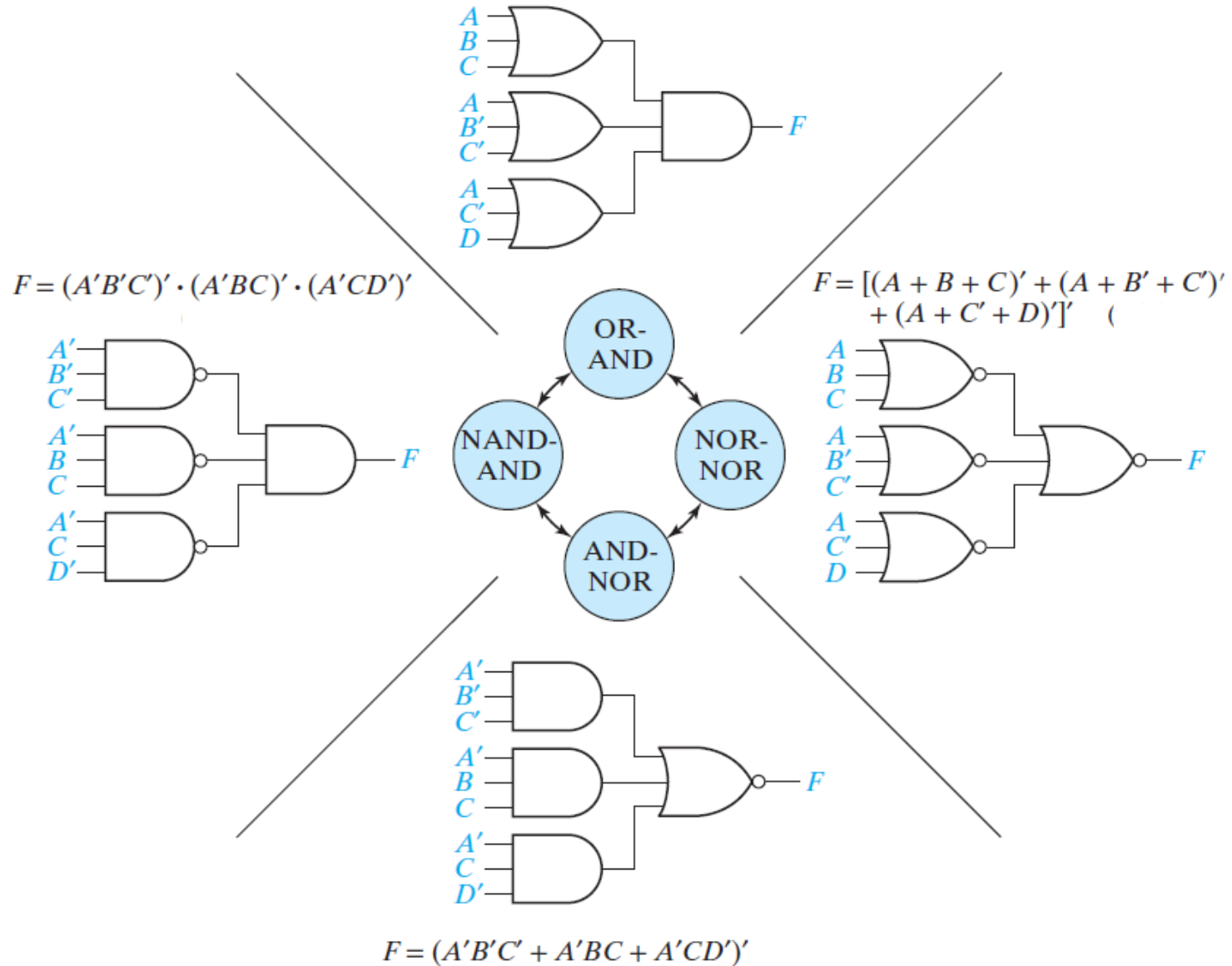


2-level Circuits



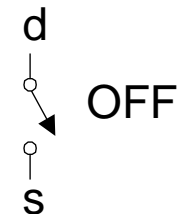
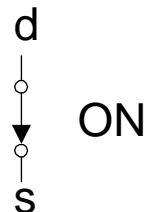
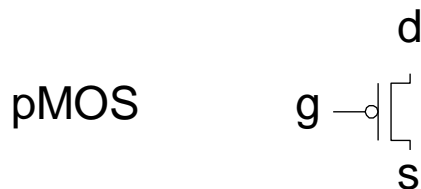
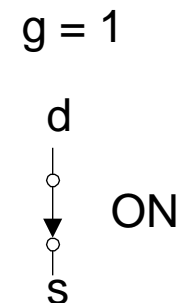
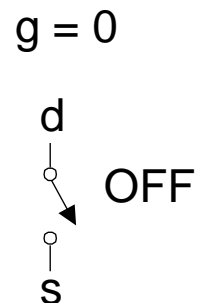
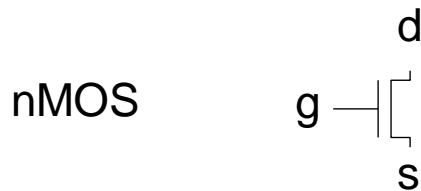
2-level Circuits

$$F = (A + B + C)(A + B' + C')(A + C' + D)$$



Transistors as Switches

- We can view MOS transistors as electrically controlled switches
- Voltage at gate controls path from source to drain

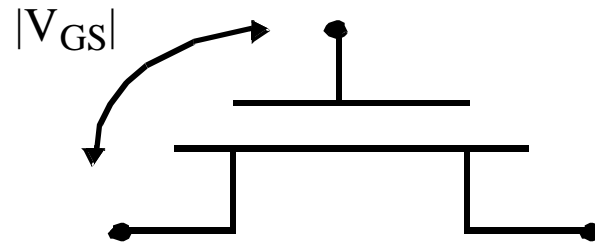
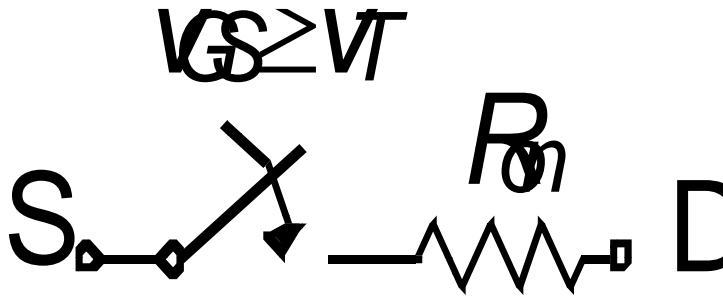


What is Transistor?

A Switch!

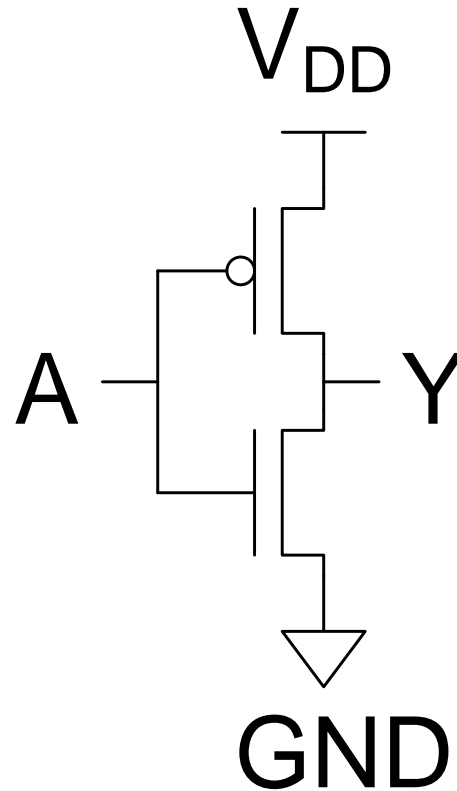
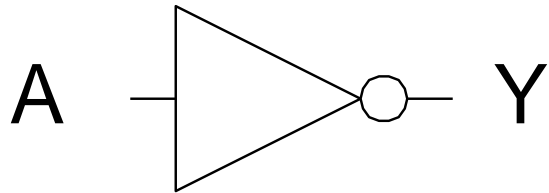


An MOS Transistor



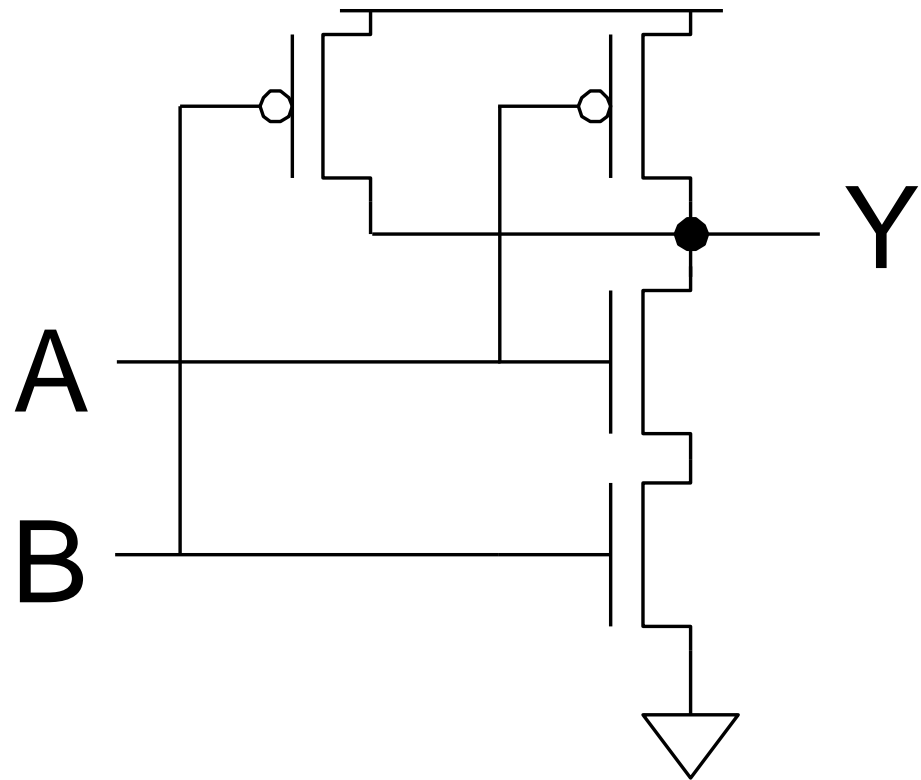
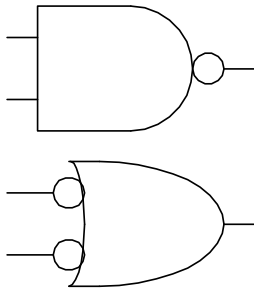
CMOS Inverter

A	Y
0	1
1	0



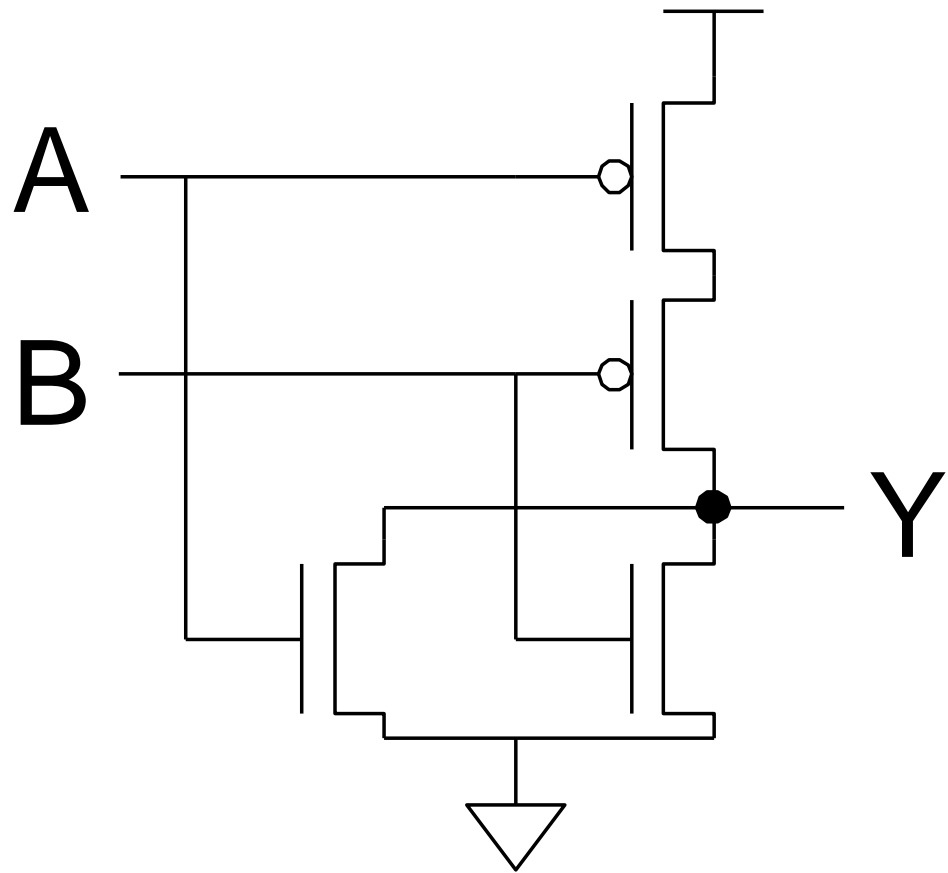
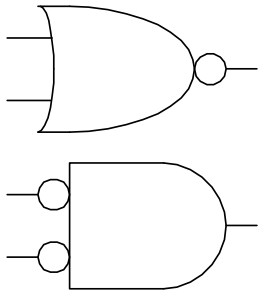
CMOS NAND Gate

A	B	Y
0	0	1
0	1	1
1	0	1
1	1	0



CMOS NOR Gate

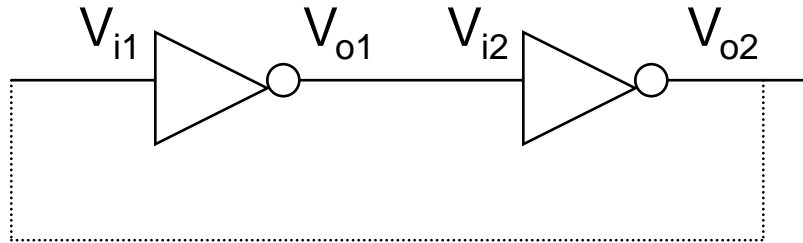
A	B	Y
0	0	1
0	1	0
1	0	0
1	1	0



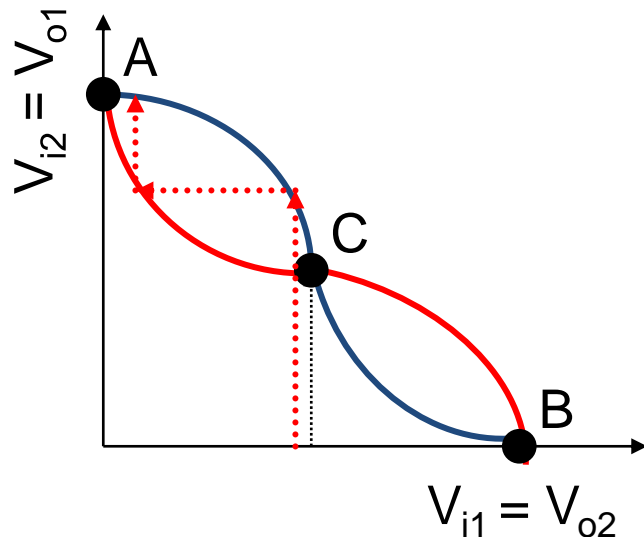
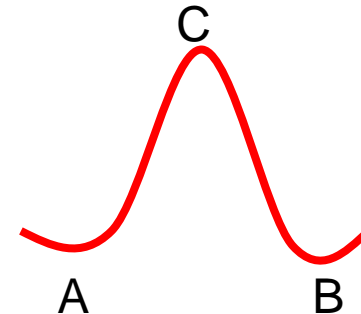
Basic Logic for Digital System in CMOS ICs

- Combination logic
 - ◆ Control switch (MUX)
 - ◆ Computation (XOR)
 - ◆ Basic logic – INV, NAND, NOR
- Sequential circuits & Finite State Machine (FSM)
 - ◆ Storage element (Latch, Flip-Flop)
- Data storage
 - ◆ Register file, SRAM, eDRAM, eFlash...
- I/O (input/output)
 - ◆ ESD protection, driving ability, level-sensing

The Regenerative Property for SRAM



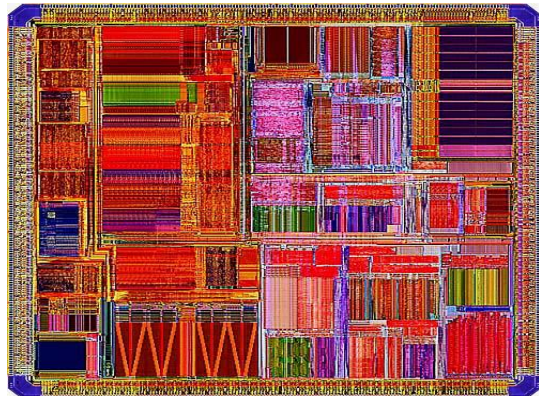
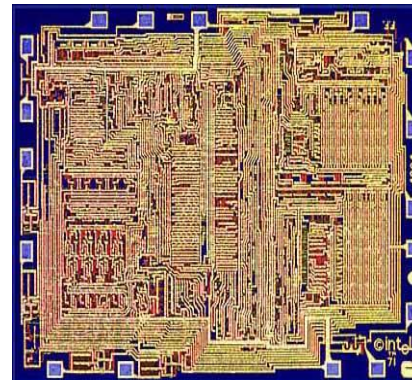
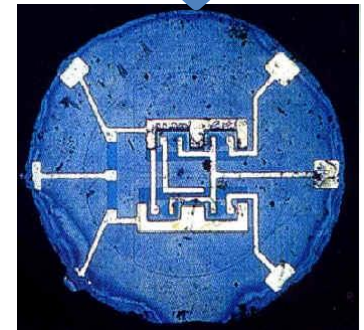
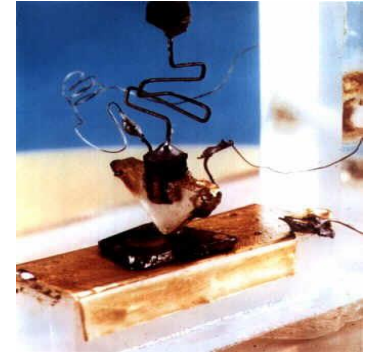
cascaded inverters



If the gain in the transient region is larger than 1, only A and B are stable operation points. C is a **metastable** operation point.

How to put together millions of transistors?

- Well chosen design methodologies
- Well chosen architectures
- Extensive use of power full CAD tools
- Strict design management
- Well chosen testing methodologies
- Design re-use
- One can NOT use same design methodologies and architectures when complexity increases orders of magnitude



General Principles

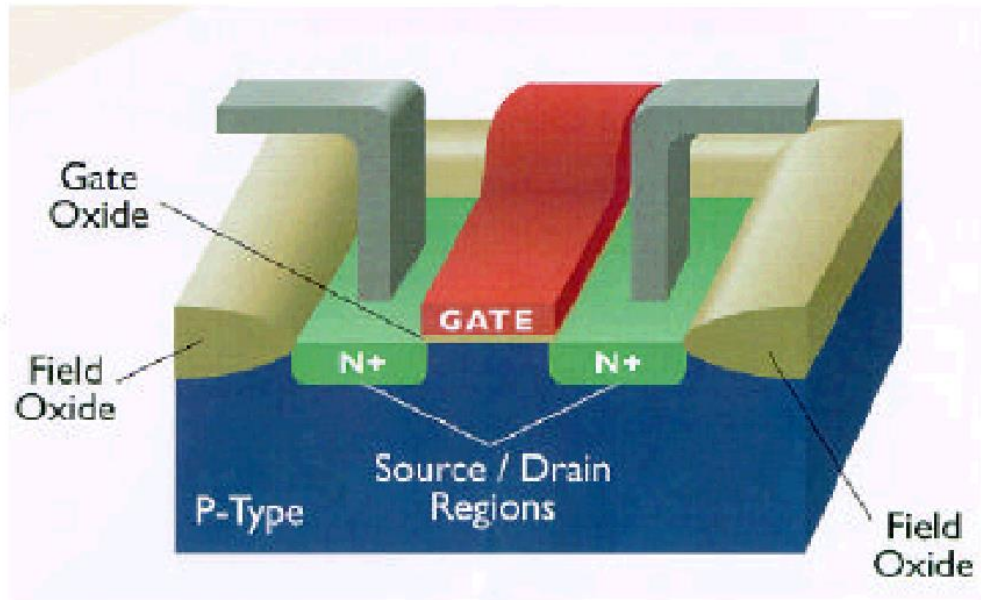
- **Technology changes fast => important to understand general principles**
 - ◆ optimization, tradeoffs
 - ◆ work as part of a group
 - ◆ leverage existing work: programs ,building blocks
- **Concepts remain the same:**
 - ◆ Example: relays -> tubes -> bipolar transistors -> MOS transistors -> FinFET -> GAAFET (MBCFET)



Future Trend for advanced technology nodes or 3DIC

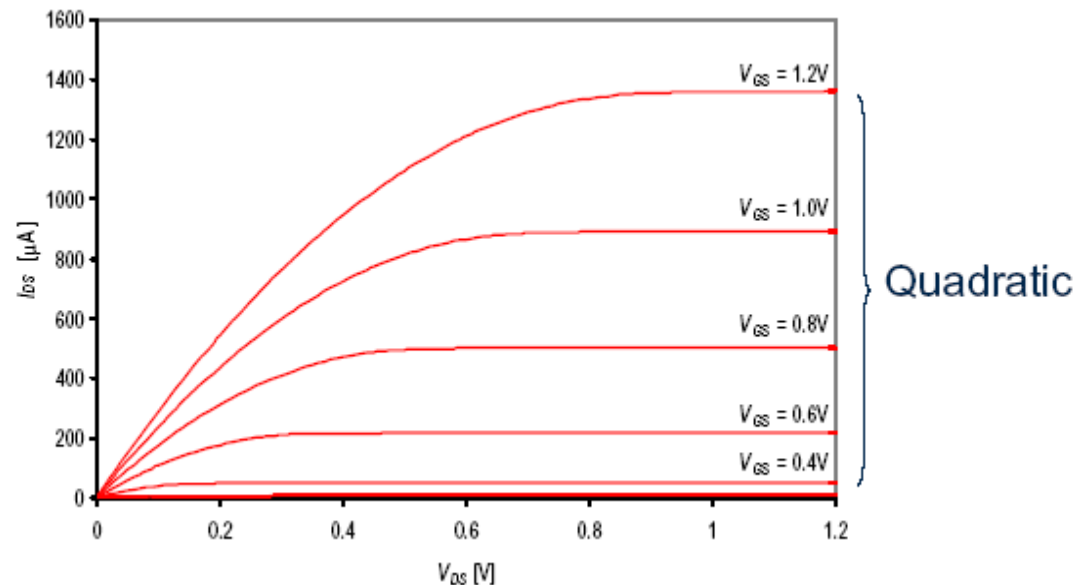
DTCO: Design-technology co-optimization

MOS Transistor: 3D Perspective

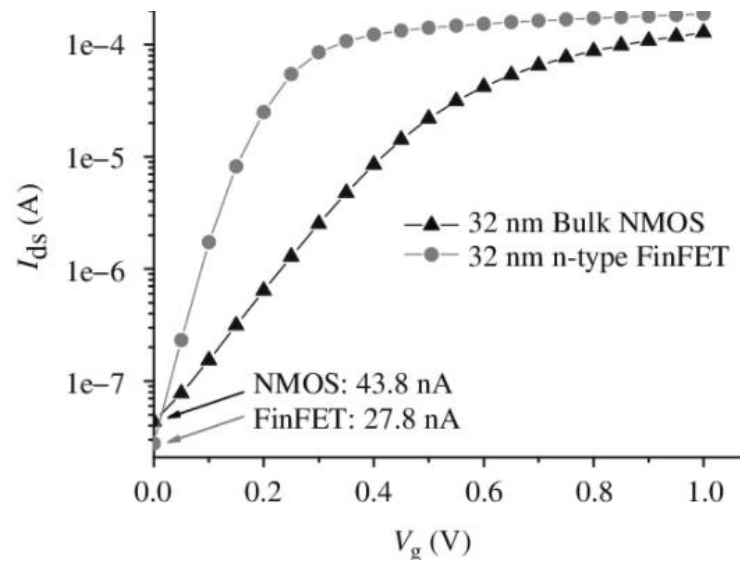
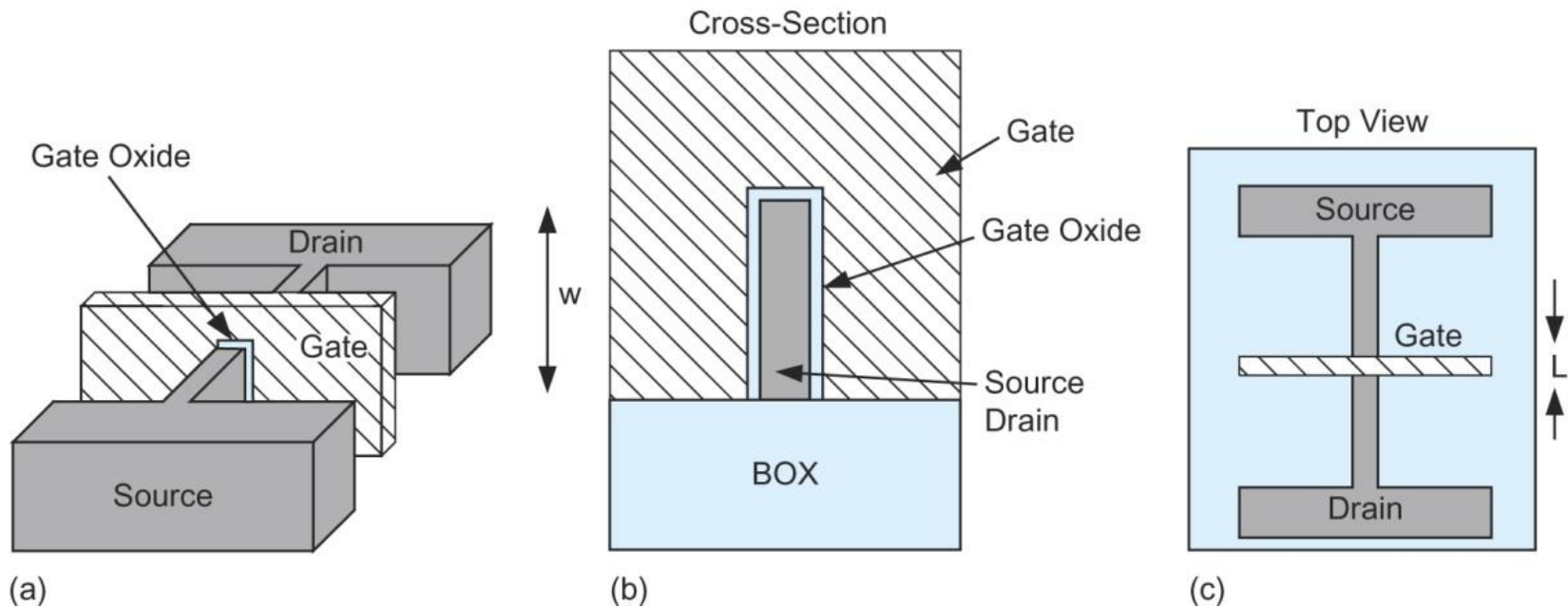


$$I_{DS} = \frac{W}{L} \mu C_{ox} \left(V_{GS} - V_{Th} - \frac{V_{DS}}{2} \right) V_{DS}$$

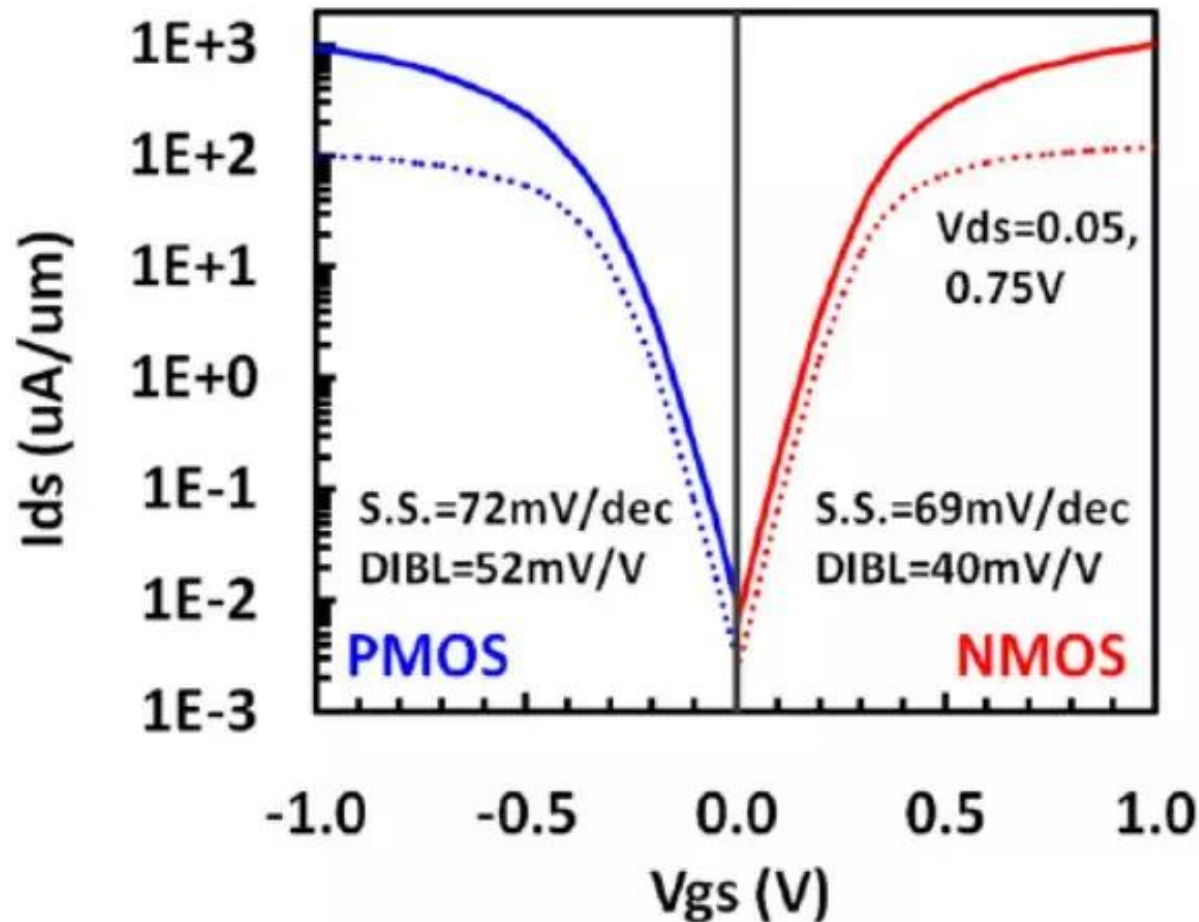
$$I_{DS} = \frac{W}{2L} \mu C_{ox} (V_{GS} - V_{Th})^2$$



FinFET

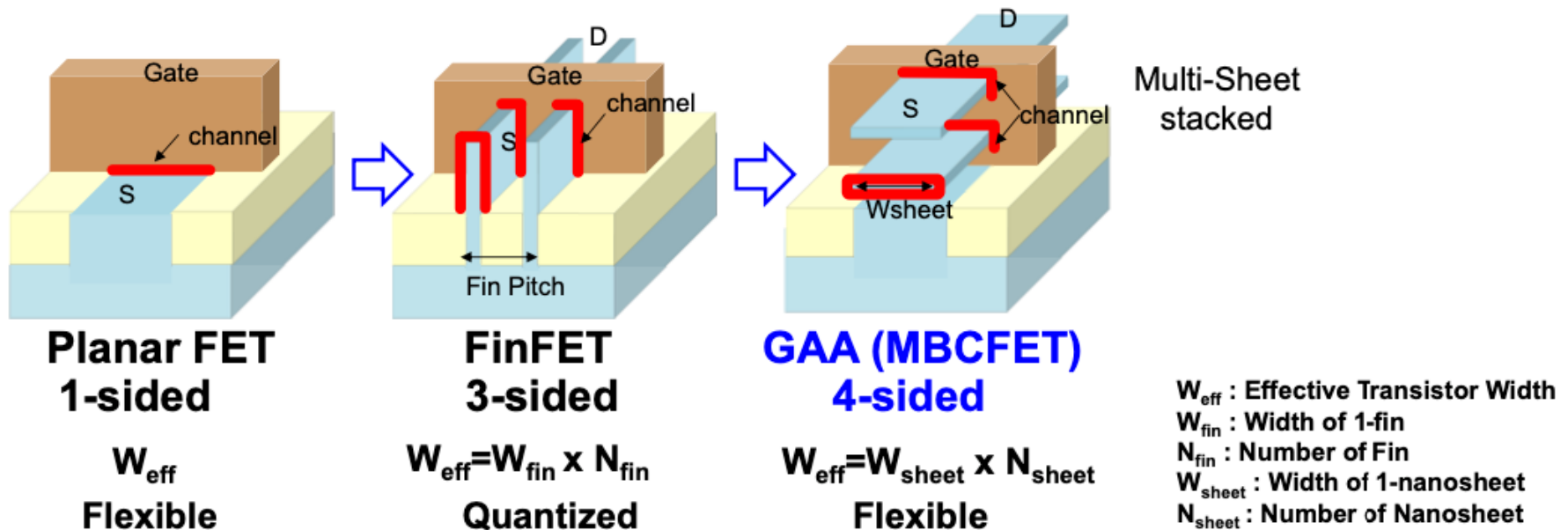


Complementary Characteristics



GAAFET, MBCFET, RibbonFET

- Transistors have evolved to provide better PPA for designers
- GAA is the ultimate transistor with 4-sided channel
 - ◆ GAA flexible W_{eff} provides more freedom to optimize PPA

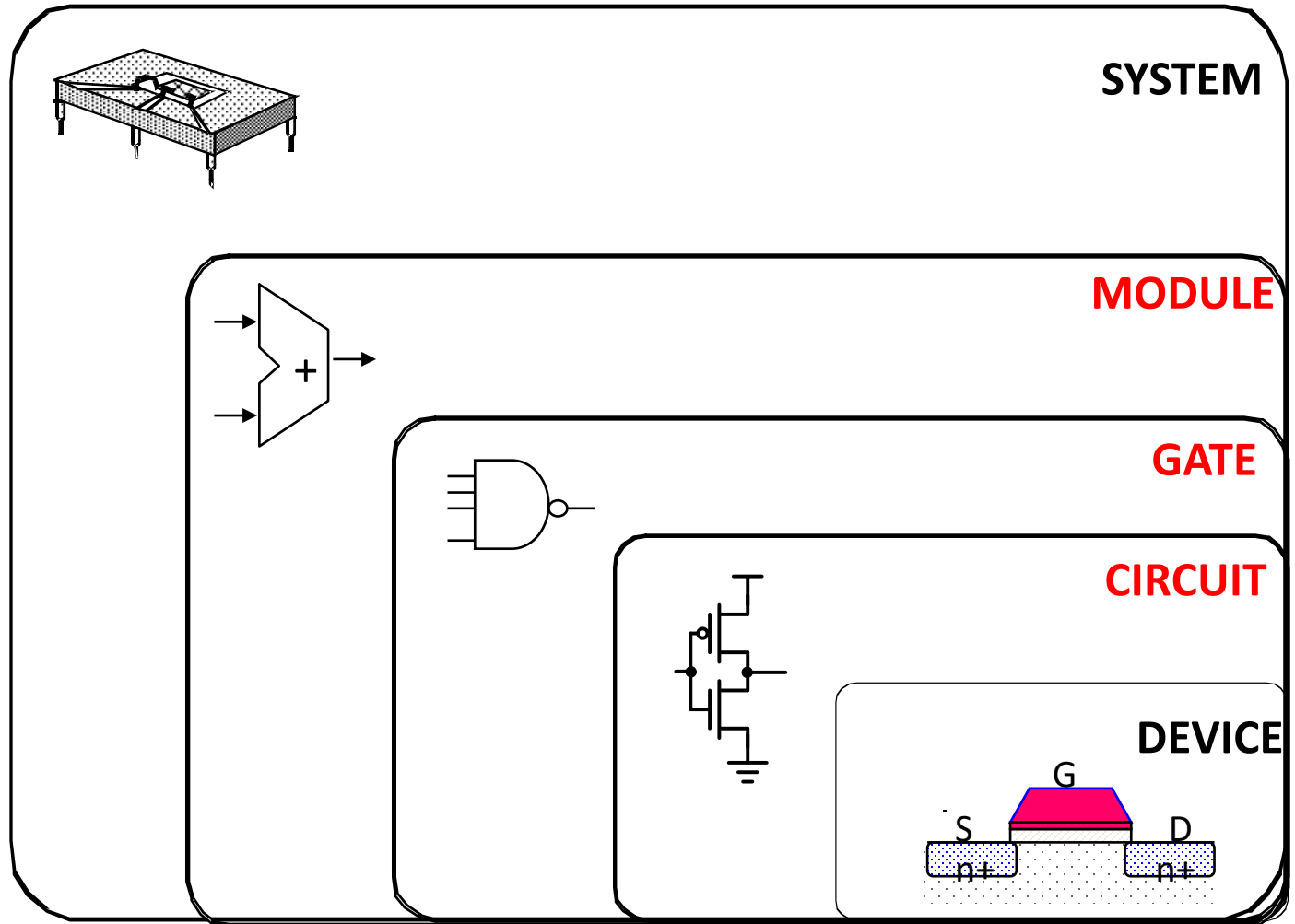


Design Abstraction Levels

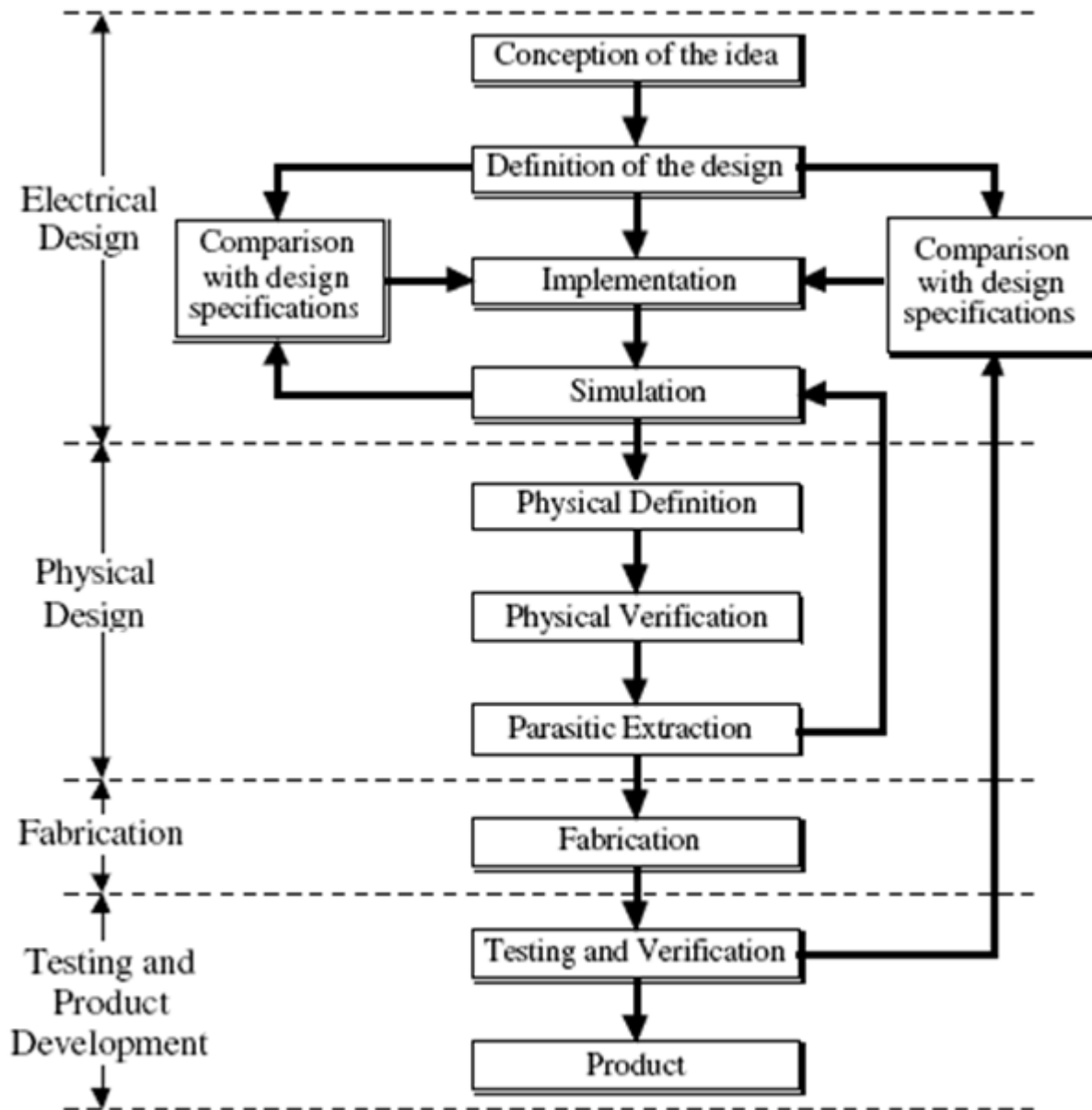
Top-Down
Design



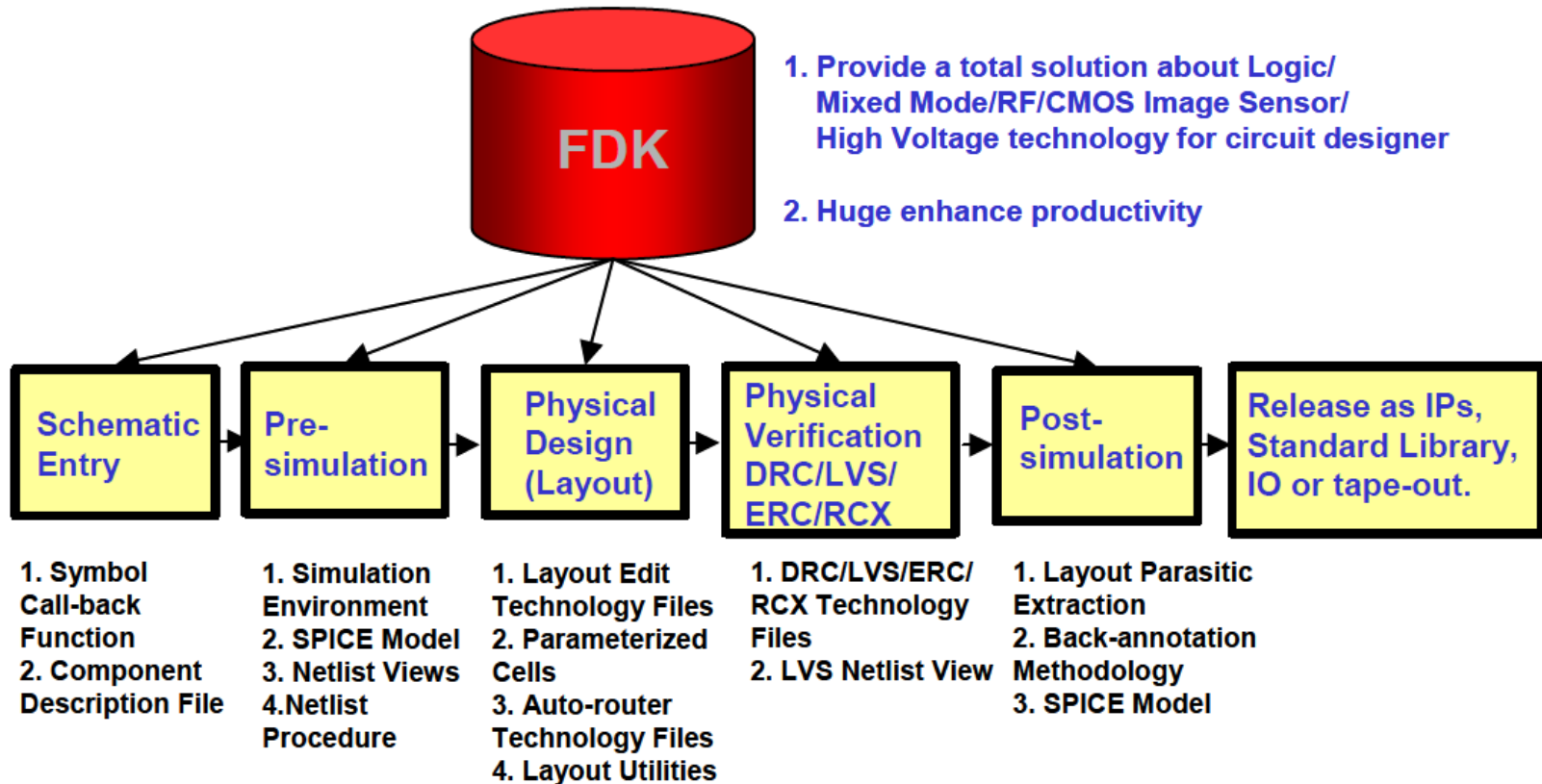
Bottom-Up
Library



Typical IC Design Flow (Methodology)



Foundry Design Kit (FDK, PDK)



Full-Custom Design

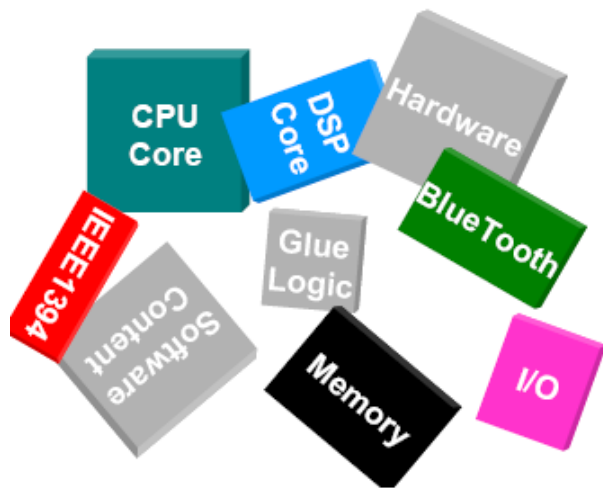
- Design some or all of the circuits, logic cells, layout specifically
 - ◆ Required cells/IPs are not available
 - ◆ Existing cell libraries can not meet the requirements
 - Area, speed or power consumption
 - ◆ Technology migration (analog or mixed-mode design)
 - ◆ Demand long design time

Cell-based (IP-Based) Design

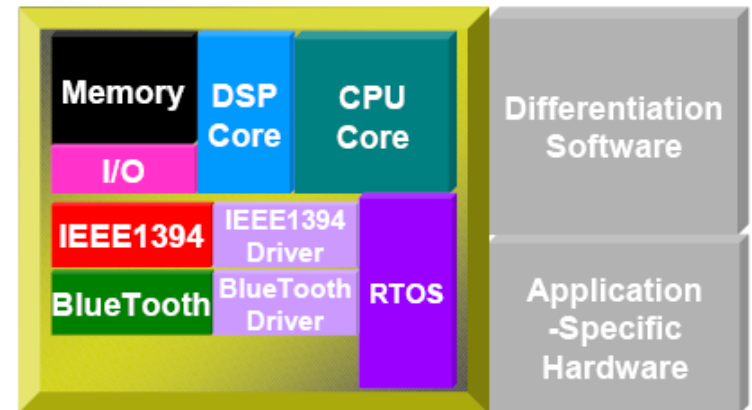
- Use pre-designed logic cells (known as standard cells) and micro cells or IPs
- Each standard cell can be optimized individually
- All mask layers are customized
- Custom blocks can be embedded

System Design Paradigm

- ◆ Data computation (functional IP)
- ◆ Data communication (platform)
- ◆ Data storage (memory)

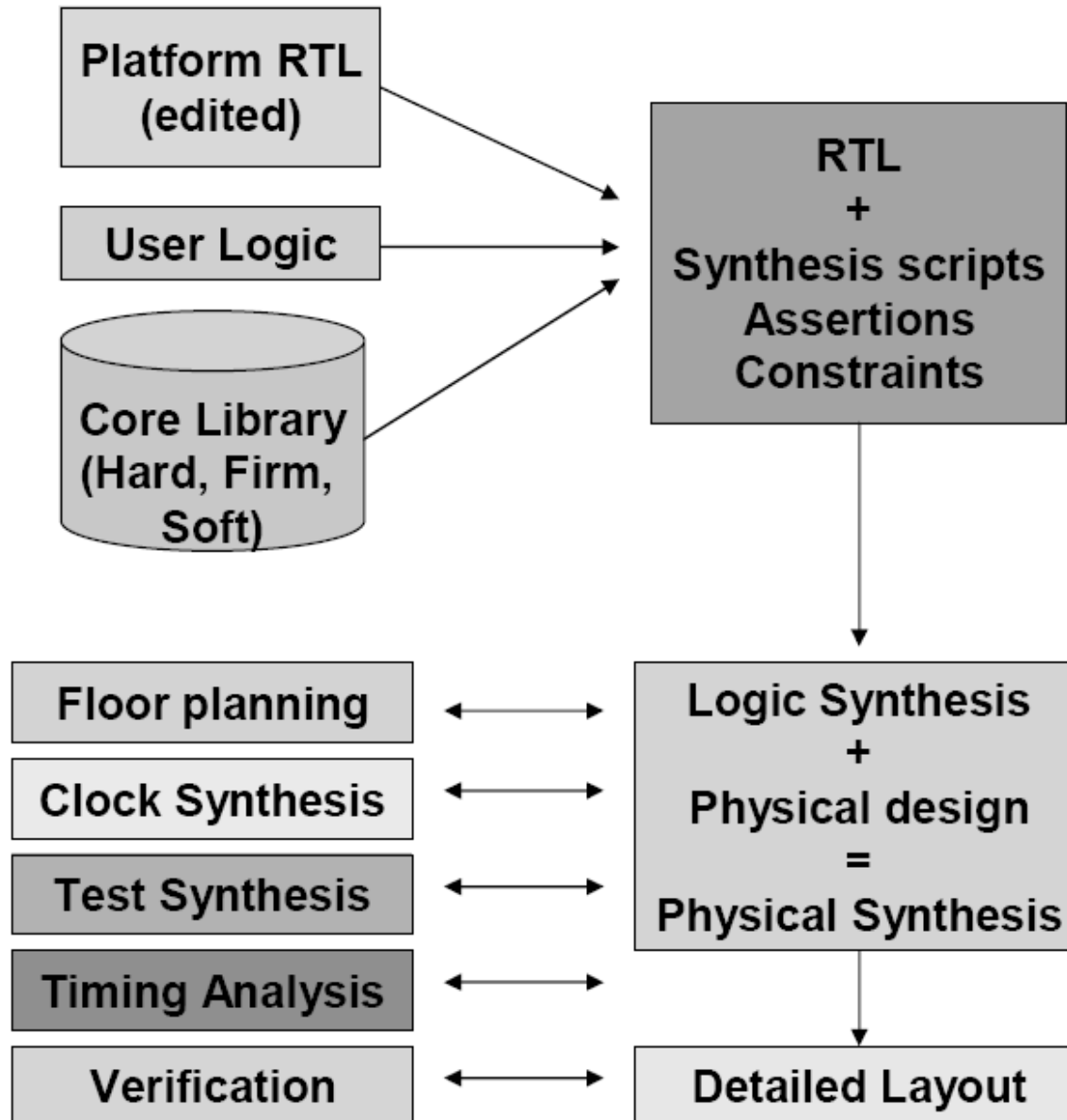


Block-Based Design



Platform-Based Design

SoC Hardware Design Methodology

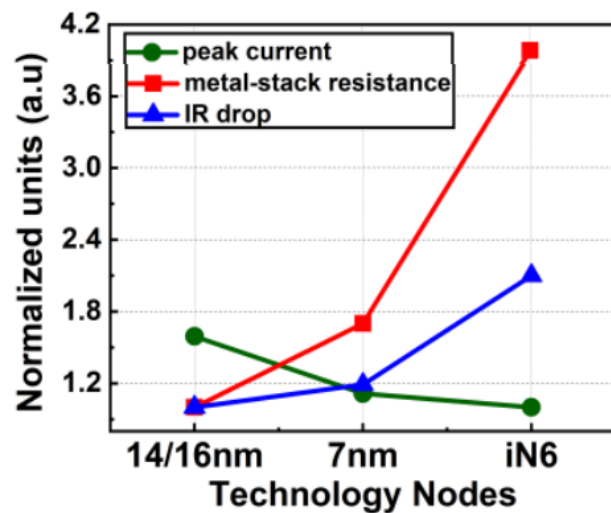


Design Metrics

- Evaluate performance of a digital circuit and System
 - ◆ Cost
 - ◆ Speed (delay, operating frequency)
 - ◆ Power dissipation
 - ◆ Energy to perform a function
 - ◆ Robustness
 - ◆ Reliability
 - ◆ Scalability

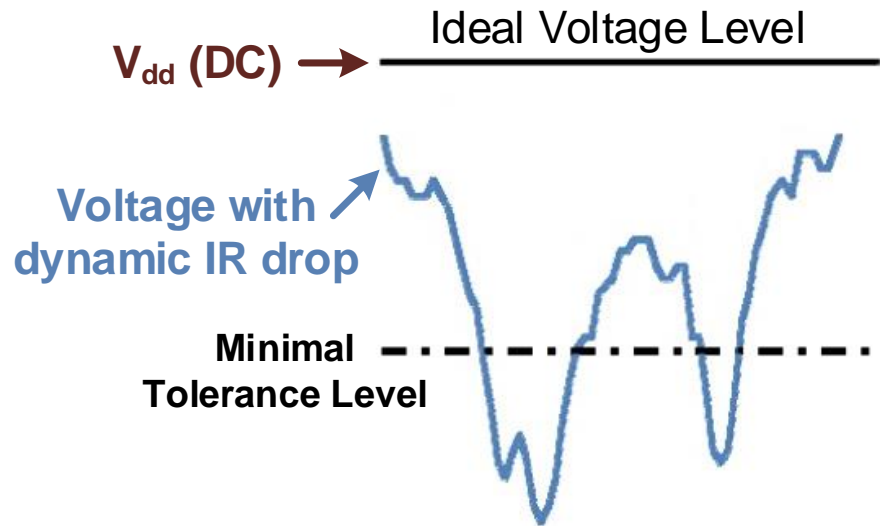
Design Challenges for Future IC Design

- Large variations
- Increasing leakage current
- Increasing RC of Interconnects
- Power integrity (large power noises)



[IEDM'19]

Static IR drop



Dynamic IR drop

Problems of Wire Delay

- Wire loading: timing optimization is based on a wire loading model.
- Loading of gate = input capacitance of following gates + wire capacitance
 - ◆ Gate loading known by synthesizer
 - ◆ Wire loading must be estimated
 - ◆ R-C delay calculation very complicated

